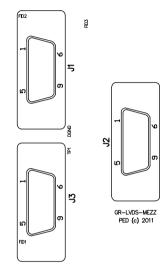
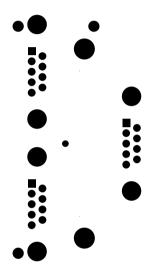


Top Silkscreen .GTO



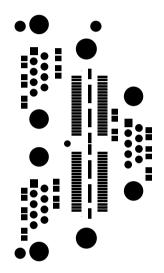
Top paste mask .GTP





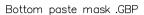
Top solder mask .GTS

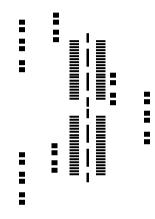




Bottom solder mask .GBS

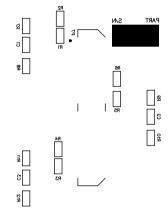




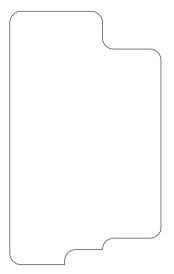




Bottom Silkscreen .GBO

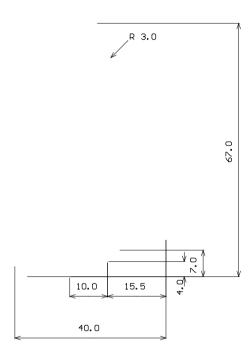




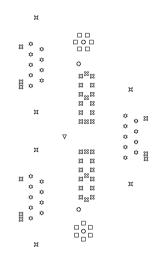


Mechanical 1 .GM1













Drill drawing .GD1

Symbol	Hit Count	Finished Hole Size	Plated	Hole Type
×	39	0.35mm (13.78mil)	PTH	Round
	12	0.5mm (19.685mil)	PTH	Round
▽	1	0.9mm (35.433mil)	PTH	Round
0	2	1.02mm (40.157mil)	NPTH	Round
**	27	1.2mm (47.244mil)	PTH	Round
0	2	2.7mm (106.299mil)	PTH	Round
Ħ	6	3.2mm (125.984mil)	PTH	Round
	89 Total			

Drilling Details.

All dimensions are finished sizes

Dimensions are in mm

Board Characteristics

Type: 4 layer Material: FR4

Thickness: 1.6mm +/-0.1mm
Contour: Milled, acc. Layer 'Mechanical 1'

Layer Stack-up

1: Top Layer 35 um Cu (End)
2: Internal Plane 1 35 um Cu (neg plane)
3: Internal Plane 2 35 um Cu (neg plane)
4: Bottom Layer 35 um Cu (End)

Plating

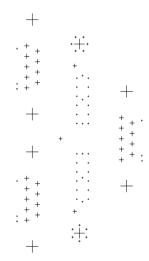
Through holes, plated, minimum 20 um Cu

<u>Tinning</u>

Pb Free

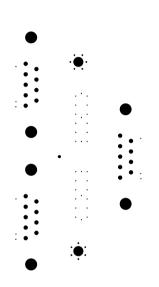
<u>Silkscre</u>en

Top Silkscreen Required (Bottom optional)





Drill guide layer .GG1



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